Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model [List multiple models if applicable.]
HP Omni 120 PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother board, Convertor board, Memory module*2	4
Batteries	All types including standard alkaline and lithium coin or button style batteries Coin cell battery	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LCD panel	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	Power cord	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	Power supply case	1
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release captive screws and remove Real cover assy
2. Release screws and remove stand assy
3. Release screws and remove M/B shielding assy
4. Release screws and remove Wireless module (figure.1)
5. Remove Memory module (figure.3)
6. Release captive screws and remove Thermal module
7. Release screws and remove Mother board (figure.4)
8. Release screws and remove System fan
9. Release captive screws and remove HDD module
10. Release captive screw and remove ODD module
11. Release screws and remove Convertor board (figure.2)
12. Release screws and remove Webcam module
13. Release screws and remove Speaker module
14. Release screws and remove middle frame assy
15. Release screws and remove LCD module
16. LCD panel disassembly(Figure 5)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
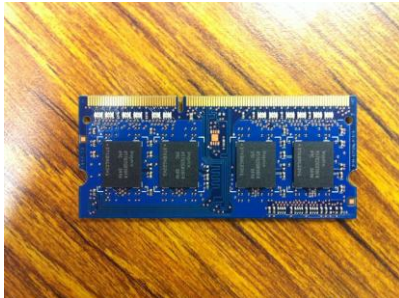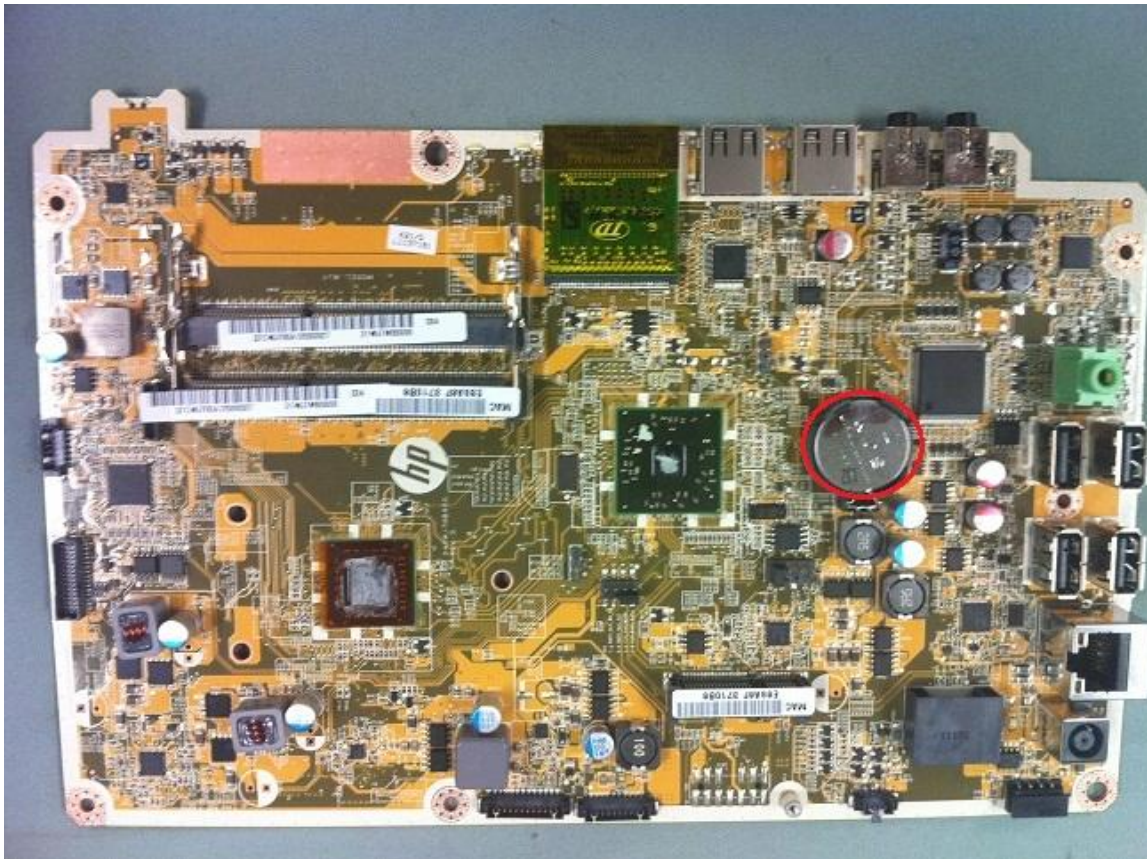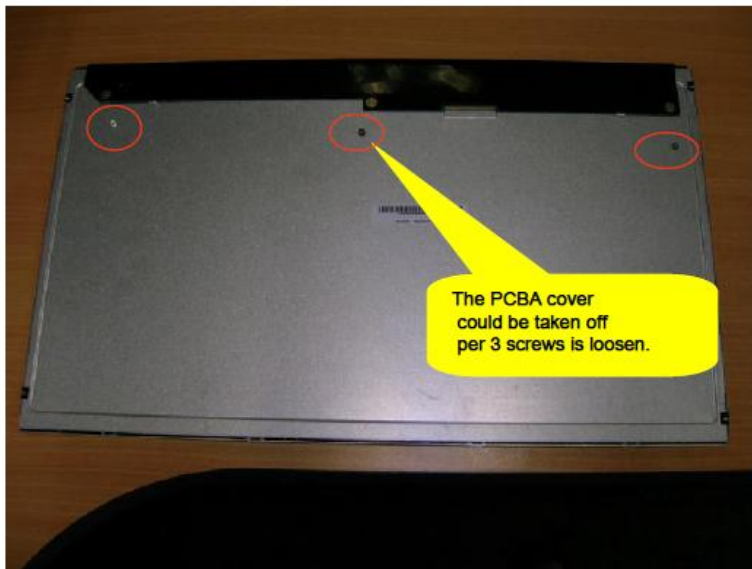
1. Wireless module

PSG instructions for this template are available at EL-MF877-01

2. Convertor board
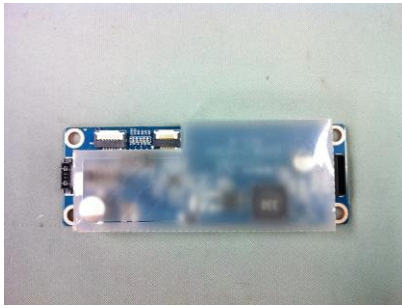
3. Memory module

4. Mother board

PSG instructions for this template are available at EL-MF877-01

5. LCD panel disassembly process

1.Remove screws in the shielding plat of panel

The PCBA cover could be taken off per 3 screws is loosen.

2. Tear off the PCBA mylar

FPC must be avoided bending or scratch when PCBA has been spread.

FPC (Flexible Printed Circuit)

3. Remove the front bezel

Before disassemble the front bezel from panel, the hook on the bezel must be loosen first.

Front bezel

PSG instructions for this template are available at EL-MF877-01
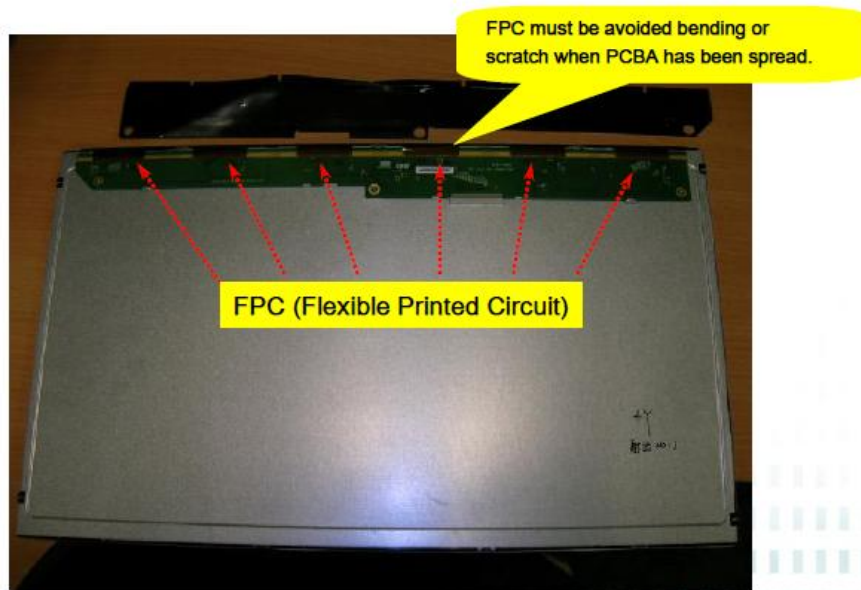
4. Take off the TFT glass from B/L module

To take off the glass from B/L Module and spread out the PCB.
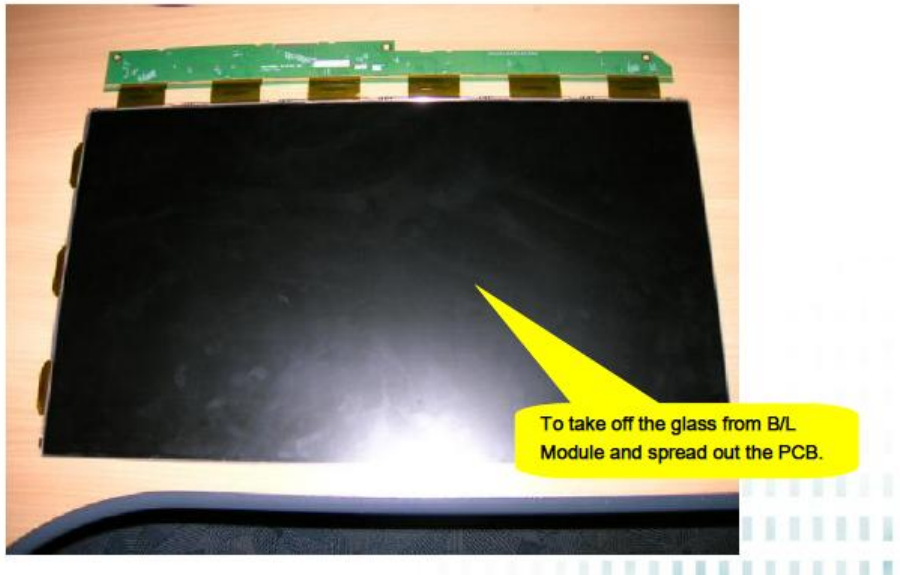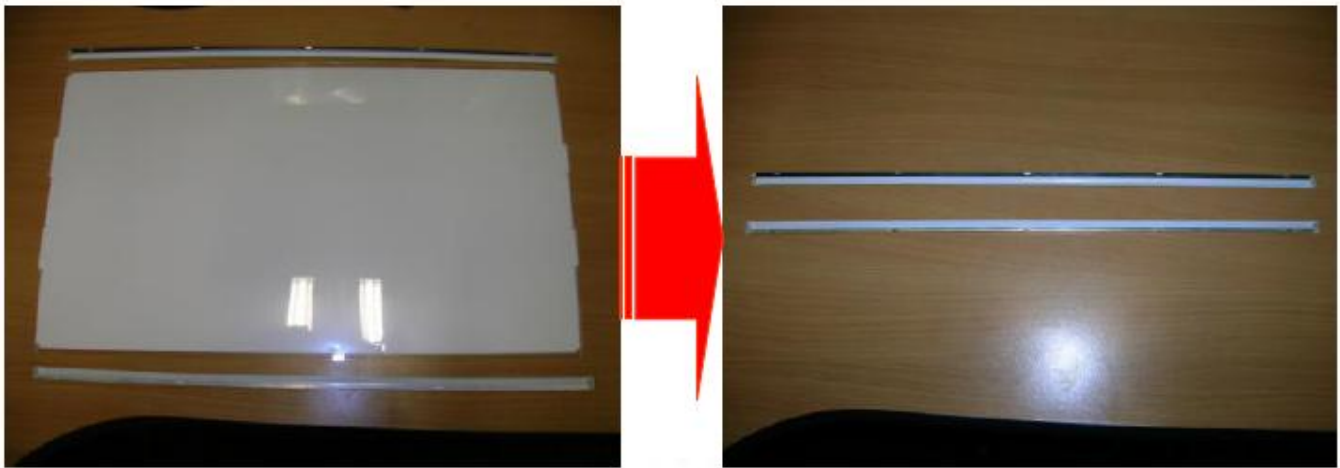
5. Take off frame from B/L module

6. Separate optical layers of B/L module

7. Take off LED light bar from B/L module

8. Disassemble the power supply case parts.

Cutting here
& separated

Cutting here
& separated

Cutting here
& separated

Cutting here
& separated

Remove PCBA

Cutting here
& separated

Template Revision B

PSG instructions for this template are available at EL-MF877-01